

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Cancelled)

2. (Currently Amended) A method of manufacturing a thin film magnetic head according to claim 45, wherein the uniform width portion is formed through a plating process by using ~~at the predetermined~~ magnetic material including iron, nickel and cobalt in the third step.

3. (Currently Amended) A method of manufacturing a thin film magnetic head according to claim 45, wherein the uniform width portion is formed through sputtering and an etching process by using ~~at the predetermined~~ magnetic material including either a cobalt iron alloy or a cobalt iron alloy oxide as an amorphous alloy in the third step.

4. (Currently Amended) A method of manufacturing a thin film magnetic head according to claim 45, wherein the fourth step is performed at ~~at the~~ ambient temperature within a range of 150°C to 250°C.

5. (Currently Amended) A method of manufacturing a thin film magnetic head according to claim 1, comprising:

a first magnetic layer and a second magnetic layer magnetically coupled to each other and having two magnetic poles facing each other with a gap layer in between near and in a recording-medium-facing surface to be faced with a recording medium;

a thin film coil provided between the first and second magnetic layers; and
an insulating layer for insulating the thin film coil from the first and the second magnetic layers, the second magnetic layer including a uniform width portion which defines a recording track width of the recording medium;

wherein the method comprises:

a first step of forming the first magnetic layer on a substrate through sputtering by using a magnetic material including iron nitride;

a second step of forming the gap layer on the first magnetic layer;

a third step of selectively forming at least the uniform width portion in the second magnetic layer on the gap layer by using a predetermined magnetic material, the uniform width portion extending so as to cross over a position in which the recording-medium-facing surface is to be formed; and

a fourth step of selectively removing the gap layer in a region other than a portion corresponding to the uniform width portion, through reactive ion etching with the uniform width portion as a mask, wherein the gap layer is selectively removed in an atmosphere of gas including chlorine and boron trichloride, and at an ambient temperature within a range of 30°C to 300°C, and selectively removing the and the first magnetic layer in a region other than a portion corresponding to the uniform width portion to a predetermined depth, through reactive ion etching with the uniform width portion as a mask, is selectively removed in an atmosphere of gas including chlorine in the fourth step, and at an ambient temperature within a range of 30°C to 300°C.

6. (Currently Amended) A method of manufacturing a thin film magnetic head according to claim 5, wherein the gap layer is selectively removed in ~~at the~~ gas atmosphere built by setting an amount of the chlorine gas to be supplied within a range of 20 to 40 milliliters per minute and setting an amount of the boron trichloride gas to be supplied within a range of 60 to 80 milliliters per minute, and the first magnetic layer is selectively removed in a gas atmosphere build by setting an amount of the chlorine gas to be supplied within a range of 100 to 200 milliliters per minute.